Title (en)

SOLDERING PROCEDURE FOR FIXING AN ELEMENT AS FOR EXAMPLE A SUBSTRATE OF A HYBRID CIRCUIT ON A HEAT DISSIPATING BASE

Publication

EP 0443483 B1 19930407 (FR)

Application

EP 91102264 A 19910218

Priority

FR 9002277 A 19900223

Abstract (en)

[origin: EP0443483A1] This procedure is such that the metallisation effected on the said element, and necessary for the behaviour (integrity) of the soldering, is effected according to a discontinuous pattern (4), such that the dimensions of the non-metallised areas (5) are reduced to dimensions which do not run the risk of deterioration of the said element in operation. <IMAGE>

IPC 1-7

H05K 3/10; H05K 3/34; H05K 7/20

IPC 8 full level

H01L 21/48 (2006.01); **H05K 3/34** (2006.01); **H05K 7/20** (2006.01); H05K 1/09 (2006.01); H05K 1/11 (2006.01); H05K 3/00 (2006.01)

CPC (source: EP)

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